**2019 IEEE International Conference on**

**Smart Manufacturing, Industrial & Logistics Engineering (SMILE2019) &**

**2019 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2019)**

**April 19-21, 2019, Zhejiang University, Hangzhou, China**

Conference [Honorary](http://www.baidu.com/link?url=X8_aGQOLLWPYw3HLF8rAJXblzZLgWP3kifTJ-VRQQQT8bEjP4mDiho2VwauK0dR9jsXI2NjNtaNAkaAdPUvtC8RWXlsZakgtP_OpSj2CCWe) Chair: Professor Andrew Kusiak, University of Iowa Informatics Initiative

Conference Chair: Professor Chen-Fu Chien, Taiwan Tsing Hua University

(<http://smile.ieeng.org/>)

The accepted papers will indexed by EI Compendex.

Selected papers will be recommended for reviews and possible publications in special issues of SCI journals.

**Aims and Topics:**

The joint conference of 2019 IEEE International Conference on Smart Manufacturing, Industrial & Logistics Engineering (SMILE2019) and 2019 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2019) aims to disseminate recent theoretical and methodological developments, applications, and case studies in light of ongoing revolutions for manufacturing intelligence and smart manufacturing including, yet not limited, the following topics:

Big Data Analytics & Data Mining for Smart Manufacturing Industry 4.0 & Cyber-Physical Systems

AI & Computational Intelligence for Smart Manufacturing Advanced Process Control/ Advanced Equipment Control

Internet of things (IOT) Virtual Metrology, Tool Health, Fault Detection & Classification

Manufacturing Intelligence, Evolutionary Algorithms Circular Economics, Green Supply Chain & Sustainability

Decision Technologies, Modeling & Decision Analysis Augmented Reality, Virtual reality

Simulation Optimization & Applications Manufacturing Strategy & Manufacturing Innovation

Corporate Resource Planning & ERP User Experience & Innovative Design

Smart Production Facilities & Green Fab Human-machine Collaboration, Ergonomics & Safety

Predictive Maintenance, Quality & Reliability Total Resource Management & Overall Resource Effectiveness

Semiconductor & High-tech Manufacturing Applications of Industrial Engineering & Logistic

**Keynote Speakers and Distinguished Guests**

Professor Andrew Kusiak, the University of Iowa, USA, Editor-in-chief of Journal of Intelligent Manufacturing

Professor Tae-Eog Lee, Korea Advanced Institute of Science and Technology (KAIST), South Korea, President of Korea Institute of Industrial Engineers (KIIE)

Professor Hing Kai Chan, Ningbo Nottingham University, China, Co-editor of Industrial Management & Data Systems

Professor Dauzère-Pérès, Stéphane, École des Mines de Saint-Étienne – Georges Charpak Campus, France

Professor McGinnis, Leon F., Georgia Institute of Technology, USA

Professor Ehm, Hans, Supply Chain Innovation, Infineon Technologies AG, Germany

Professor Lee, Gyu M., Pusan National University, South Korea, Editor-in-Chief of International Journal of Industrial Engineering: TAP

Professor Gen, Mitsuo, Fuzzy Logic Systems Institute, Japan, Editor-in-Chief of Industrial Engineering & Engineering Management

More experts will join us soon……

**Submission:**

All papers must be written in English with a maximum length of 5 pages. For paper format, submission, and related information, please visit: <http://smile.ieeng.org/> and submission page: <https://easychair.org/conferences/?conf=smile2019>. For the accepted papers, please download Copyright in conference website by yourself, and send back to email:[smile\_ismi2019@163.com](mailto: smile_ismi2019@163.com)

**Important Dates:**

Deadline for submission of abstract/ special session proposals: December 1, 2018

Deadline for Full Paper Submission for EI indexed proceedings for IEEE Xplore: December 31, 2018

Deadline for Full Paper/Extended Abstract Submission: January 31, 2019

Camera Ready Manuscript Submission: February 28, 2019

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